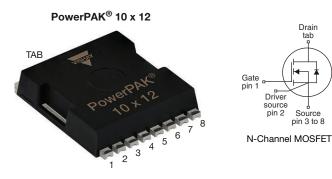
## SiHK185N60E



**Vishay Siliconix** 

## **E Series Power MOSFET**



| PRODUCT SUMMARY                            |                 |       |  |  |  |
|--|-----------------|-------|--|--|--|
| V <sub>DS</sub> (V) at T <sub>J</sub> max. | 650             |       |  |  |  |
| R <sub>DS(on)</sub> typ. (Ω) at 25 °C      | $V_{GS} = 10 V$ | 0.160 |  |  |  |
| Q <sub>g</sub> max. (nC)                   | 33              |       |  |  |  |
| Q <sub>gs</sub> (nC)                       | 7               |       |  |  |  |
| Q <sub>gd</sub> (nC)                       | 11              |       |  |  |  |
| Configuration                              | Single          |       |  |  |  |

### **FEATURES**

- 4<sup>th</sup> generation E series technology
- Low figure-of-merit (FOM) Ron x Qg
- Low effective capacitance (Co(er))
- Reduced switching and conduction losses
- Avalanche energy rated (UIS)
- · Kelvin connection for reduced gate noise
- Material categorization: for definitions of compliance please see <u>www.vishay.com/doc?99912</u>

### APPLICATIONS

- Server and telecom power supplies
- Switch mode power supplies (SMPS)
- Power factor correction power supplies (PFC)
- Lighting
  - High-intensity discharge (HID)
  - Fluorescent ballast lighting
- Industrial
  - Welding
  - Induction heating
  - Motor drives
  - Battery chargers
  - Solar (PV inverters)

| ORDERING INFORMATION            |                    |
|---------------------------------|--------------------|
| Package                         | PowerPAK 10 x 12   |
| Lead (Pb)-free and halogen-free | SiHK185N60E-T1-GE3 |

| <b>ABSOLUTE MAXIMUM RATINGS</b> ( $T_c = 25 \text{ °C}$ , unless otherwise noted) |   |                                   |             |       |  |  |  |
|---|---|-----------------------------------|-------------|-------|--|--|--|
| PARAMETER   |   | SYMBOL                            | LIMIT       | UNIT  |  |  |  |
| Drain-source voltage  |   | V <sub>DS</sub>                   | 600         | V     |  |  |  |
| Gate-source voltage   | V <sub>GS</sub>   | ± 30                              |             |       |  |  |  |
| Continuous drain current (T <sub>J</sub> = 150 °C)                                | $V_{GS} \text{ at } 10 \text{ V} \qquad \frac{T_{C} = 25 \text{ °C}}{T_{C} = 100 \text{ °C}}$ |                                   | 19          |       |  |  |  |
|   | $V_{GS}$ at 10 V $T_C = 100 \text{ °C}$   | I <sub>D</sub>                    | 12          | А     |  |  |  |
| Pulsed drain current <sup>a</sup>   | I <sub>DM</sub>   | 44                                |             |       |  |  |  |
| Linear derating factor  |   |                                   | 0.9         | W/°C  |  |  |  |
| Single pulse avalanche energy <sup>b</sup>  | E <sub>AS</sub>   | 75                                | mJ          |       |  |  |  |
| Maximum power dissipation   |   | P <sub>D</sub> 114                |             | W     |  |  |  |
| Operating junction and storage temperature range                                  |   | T <sub>J</sub> , T <sub>stg</sub> | -55 to +150 | °C    |  |  |  |
| Drain-source voltage slope  | T <sub>J</sub> = 125 °C   | dv/dt 100                         |             | V/ns  |  |  |  |
| Reverse diode dv/dt <sup>c</sup>  |   | uv/di                             | 22          | v/IIS |  |  |  |

Notes

a. Repetitive rating; pulse width limited by maximum junction temperature

- b.  $V_{DD}$  = 120 V, starting T<sub>J</sub> = 25 °C, L = 28.2 mH, R<sub>q</sub> = 25  $\Omega$ , I<sub>AS</sub> = 2.3 A
- c.  $I_{SD} \leq I_D, \, di/dt$  = 100 A/µs, starting  $T_J$  = 25  $^\circ C$

1 For technical questions, contact: <u>hvm@vishay.com</u>

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## SiHK185N60E

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| THERMAL RESISTANCE RATI                                   | NGS                   |  |   |                       |      |       |       |      |
|---|-----------------------|--|---|-----------------------|------|-------|-------|------|
| PARAMETER   | SYMBOL                | TYP.   |   | MAX.                  |      | UNIT  |       |      |
| Maximum junction-to-ambient                               | R <sub>thJA</sub>     | - 50 <sup>a</sup>  |   |                       |      |       |       |      |
| Maximum junction-to-case (drain)                          | R <sub>thJC</sub>     | - 1.1  |   |                       |      | °C/W  |       |      |
|   |                       |  |   |                       |      |       |       |      |
| <b>SPECIFICATIONS</b> ( $T_J = 25 \ ^{\circ}C$ , u        | inless otherwi        | ise noted)   |   |                       |      |       |       |      |
| PARAMETER   | SYMBOL                | TES  | T CONDIT  | IONS                  | MIN. | TYP.  | MAX.  | UNIT |
| Static  |                       | <u>.</u>   |   |                       |      | -     |       |      |
| Drain-source breakdown voltage                            | V <sub>DS</sub>       | V <sub>GS</sub> =  | = 0 V, I <sub>D</sub> = 2   | 250 μA                | 600  | -     | -     | V    |
| V <sub>DS</sub> temperature coefficient                   | $\Delta V_{DS}/T_{J}$ | Referenc   | e to 25 °C,   | I <sub>D</sub> = 1 mA | -    | 0.63  | -     | V/°C |
| Gate-source threshold voltage (N)                         | V <sub>GS(th)</sub>   | V <sub>DS</sub> =  | = V <sub>GS</sub> , I <sub>D</sub> = 2                                  | 250 µA                | 3.0  | -     | 5.0   | V    |
|   |                       | ,  | $V_{GS} = \pm 20$   | V                     | -    | -     | ± 100 | nA   |
| Gate-source leakage                                       | I <sub>GSS</sub>      | ,  | $V_{GS} = \pm 30$   | V                     | -    | -     | ± 1   | μA   |
| 7   |                       | V <sub>DS</sub> =  | = 600 V, V <sub>G</sub>   | <sub>S</sub> = 0 V    | -    | -     | 1     |      |
| Zero gate voltage drain current                           | I <sub>DSS</sub>      | V <sub>DS</sub> = 480 V  | V <sub>DS</sub> = 480 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 125 °C |                       | -    | -     | 10    | μA   |
| Drain-source on-state resistance                          | R <sub>DS(on)</sub>   | V <sub>GS</sub> = 10 V   | ۱ <sub>D</sub>  | = 9.5 A               | -    | 0.160 | 0.185 | Ω    |
| Forward transconductance b                                | 9 <sub>fs</sub>       | V <sub>DS</sub> =  | = 20 V, I <sub>D</sub> =  | 9.5 A                 | -    | 5.3   | -     | S    |
| Dynamic   |                       |  |   |                       | •    |       |       |      |
| Input capacitance   | C <sub>iss</sub>      |  | $V_{GS} = 0 V,$<br>$V_{DS} = 100 V,$<br>f = 1 MHz                       |                       | -    | 1085  | -     | pF   |
| Output capacitance  | C <sub>oss</sub>      | - ·  |   |                       | -    | 56    | -     |      |
| Reverse transfer capacitance                              | C <sub>rss</sub>      |  |   |                       | -    | 5     | -     |      |
| Effective output capacitance, energy related <sup>b</sup> | C <sub>o(er)</sub>    |  |   |                       | -    | 59    | -     |      |
| Effective output capacitance, time related <sup>c</sup>   | C <sub>o(tr)</sub>    | $V_{DS} = 0 V$ to 400 V, $V_{GS} = 0 V$  |   | -                     | 301  | -     |       |      |
| Total gate charge   | Qg                    |  |   |                       | -    | 22    | 33    |      |
| Gate-source charge  | Q <sub>gs</sub>       | V <sub>GS</sub> = 10 V   | V <sub>GS</sub> = 10 V I <sub>D</sub> = 9.5 A, V <sub>DS</sub> = 480 V  |                       | -    | 7     | -     | nC   |
| Gate-drain charge   | Q <sub>gd</sub>       |  |   |                       | -    | 11    | -     |      |
| Turn-on delay time  | t <sub>d(on)</sub>    |  | <u> </u>  |                       | -    | 14    | 28    | 1    |
| Rise time   | t <sub>r</sub>        | -<br>V <sub>DD</sub> =   | 480 V, I <sub>D</sub> =   | = 9.5 A,              | -    | 49    | 98    | ns   |
| Turn-off delay time                                       | t <sub>d(off)</sub>   |  | = 10 V, R <sub>g</sub> =  |                       | -    | 22    | 44    |      |
| Fall time   | t <sub>f</sub>        |  |   |                       | -    | 23    | 46    | 1    |
| Gate input resistance                                     | R <sub>g</sub>        | f = 1 MHz  |   | 0.3                   | 0.7  | 1.4   | Ω     |      |
| Drain-Source Body Diode Characteristic                    | ÷                     | ·  |   |                       |      | •     |       |      |
| Continuous source-drain diode current                     | ۱ <sub>S</sub>        | MOSFET sym<br>showing the  | MOSFET symbol   |                       | -    | -     | 19    | -    |
| Pulsed diode forward current                              | I <sub>SM</sub>       | integral reverse<br>p - n junction diode   |   | -                     | -    | 44    | A     |      |
| Diode forward voltage                                     | V <sub>SD</sub>       | T <sub>J</sub> = 25 °C   | T <sub>J</sub> = 25 °C, I <sub>S</sub> = 9.5 A, V <sub>GS</sub> = 0 V   |                       | -    | -     | 1.2   | V    |
| Reverse recovery time                                     | t <sub>rr</sub>       | $T_J = 25 \text{ °C}, I_F = I_S = 9.5 \text{ A},$<br>di/dt = 100 A/µs, V <sub>R</sub> = 25 V |   | -                     | 282  | 564   | ns    |      |
| Reverse recovery charge                                   | Q <sub>rr</sub>       |  |   | -                     | 3.6  | 7.2   | μC    |      |
| Reverse recovery current                                  | I <sub>RRM</sub>      |  |   | -                     | 24   | -     | A     |      |
| ···· <b>,</b> ··· ·                                       | 1 11 11 11            |  |   | 1                     |      |       | L     |      |

### Notes

a. When mounted on 1" x 1" FR4 board

b.  $C_{oss(er)}$  is a fixed capacitance that gives the same energy as  $C_{oss}$  while  $V_{DS}$  is rising from 0 V to 400 V

c.  $C_{oss(tr)}$  is a fixed capacitance that gives the same charging time as  $C_{oss}$  while  $V_{DS}$  is rising from 0 V to 400 V

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# SiHK185N60E

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### TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

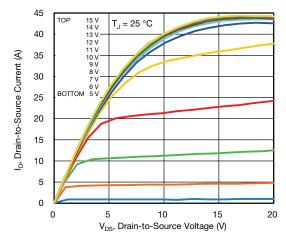


Fig. 1 - Typical Output Characteristics

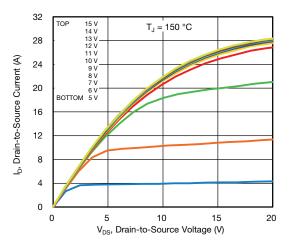


Fig. 2 - Typical Output Characteristics

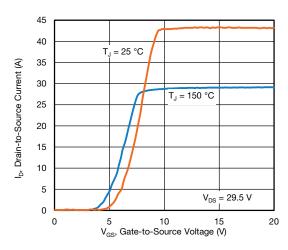


Fig. 3 - Typical Transfer Characteristics

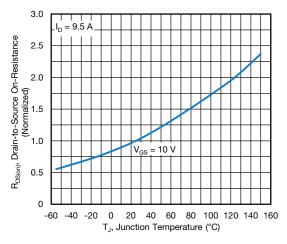


Fig. 4 - Normalized On-Resistance vs. Temperature

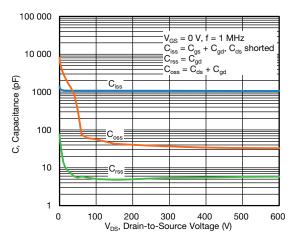


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

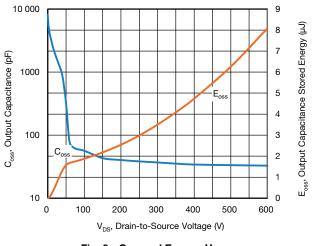


Fig. 6 -  $C_{oss}$  and  $E_{oss}$  vs.  $V_{DS}$ 

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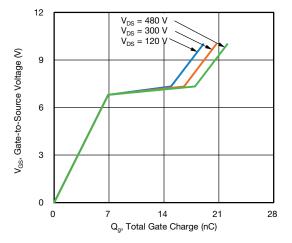


Fig. 7 - Typical Gate Charge vs. Gate-to-Source Voltage

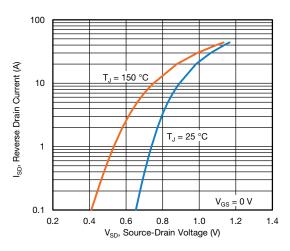


Fig. 8 - Typical Source-Drain Diode Forward Voltage

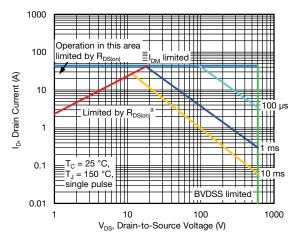


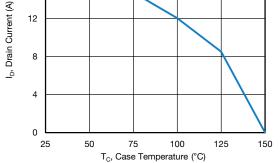
Fig. 9 - Maximum Safe Operating Area

Note

a.  $V_{GS}$  > minimum  $V_{GS}$  at which  $R_{DS(on)}$  is specified

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Fig. 10 - Maximum Drain Current vs. Case Temperature

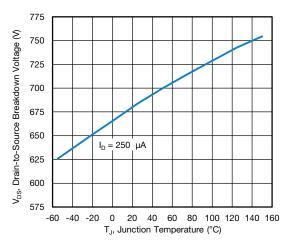
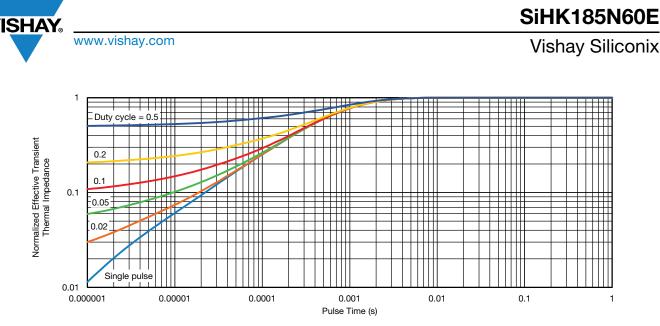


Fig. 11 - Temperature vs. Drain-to-Source Voltage

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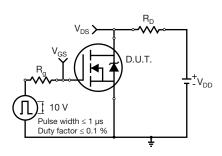


Fig. 13 - Switching Time Test Circuit

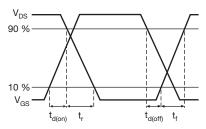


Fig. 14 - Switching Time Waveforms

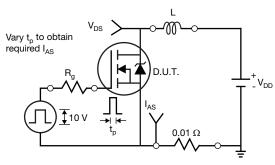


Fig. 15 - Unclamped Inductive Test Circuit

Fig. 16 - Unclamped Inductive Waveforms

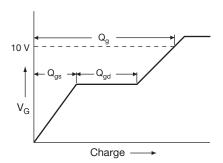


Fig. 17 - Basic Gate Charge Waveform

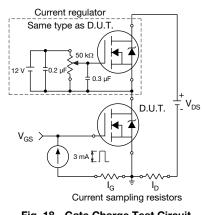


Fig. 18 - Gate Charge Test Circuit

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#### Peak Diode Recovery dv/dt Test Circuit

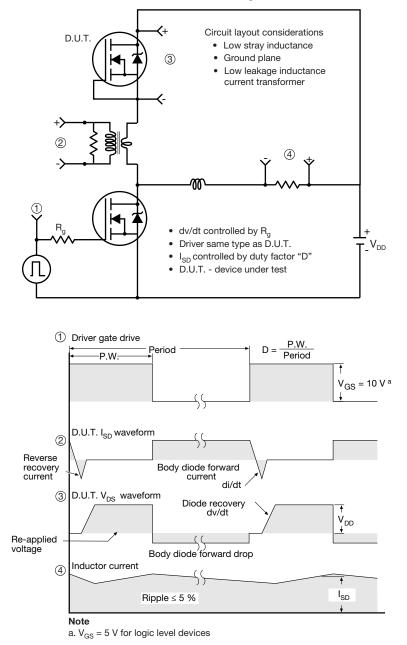


Fig. 19 - For N-Channel

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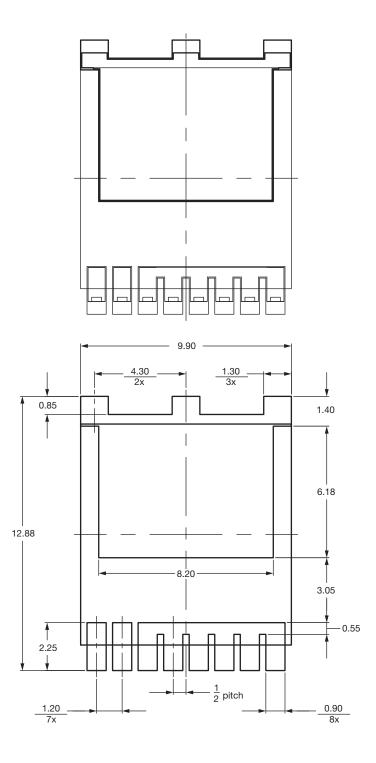
6

### **PAD** Pattern



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# Recommended Land Pattern PowerPAK<sup>®</sup> 10 x 12 (TOLL) (High Voltage)



#### Note

• Dimensions in mm

ECN: S22-1061-Rev. C, 26-Dec-2022 DWG: 3013

Revision: 26-Dec-2022

1 hnical questions, contact: hvm@vis Document Number: 92489

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